Docket No.: JCLA20832

Form 1595 (Rev. 09/04)

RECORDATION FORM COVER SHEET

U. S. Department of Commerce
Patent and Trademark Office

PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below

1. Name of conveying party(ies) with the execution date:

CHING-CHUN HSIEH, July 10, 2007

2. Name/address of receiving Party(ies)

ADVANCED SEMICONDUCTOR ENGINEERING, INC.

26, CHIN 3RD. RD., 811, NANTZE EXPORT PROCESSING ZONE, KAOHSIUNG, TAIWAN, R.O.C.

Add'1 names of receiving parties Attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment ☐ Security Agreement
☐ Merger ☐ Change of Name
☐ Reassignment ☐ Other

4. Application number(s) or patent number(s):

A. Patent Application No. (s)

11/777,738

B. Patent No.(s)

Additional number attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

J. C. Patents
4 Venture, Suite 250
Irvine, CA 92618
(949) 660-0761

Atty Docket No.: JCLA20832

6. Total No. of applications and patents involved:

ONE (1)

7. Total fee(37CFR§3.41): $ 40.00

☐ Authorized to be charged by credit card
☒ Authorized to be charge to deposit account
☐ Enclosed
☐ None required (government interest not affecting title)

8. **Payment Information**

a. Credit Card Last 4 Numbers ________.
Expiration Date ________.

b. Deposit Account Number 50-0710
Authorized User Name Jiawei Huang

9. Statement and Signature:

To the best of my knowledge and belief, the forging information is true and Correct and any attached copy is a true copy of the original document.

Jiawei Huang		7-13-2007	Total number of pages including cover sheet, attachments, and documents: 3
Name of person Signing Registration No. 43,330	Signature	Date	

ASEK1805
20832-US-PA

ASSIGNMENT

WHEREAS,

1. Ching-Chun Hsieh

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **CHIP PACKAGE STRUCTURE AND CIRCUIT BOARD THEREOF**

[ ] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Advanced Semiconductor Engineering, Inc.
of 26, Chin 3rd. Rd., 811, Nantze Export Processing Zone, Kaohsiung, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

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ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Ching Chun Hsieh Date: 2007.7.10

Sole or First Joint Inventor: Ching-Chun Hsieh

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CERTIFICATE OF TRANSMISSION

July 13, 2007

Atty Docket No.	**:**	JCLA20832
Appl. No.	**:**	11/777,738
Filing Date	**:**	July, 13, 2007
Pages	**:**	Cover + 3

BY FACSIMILE ONLY

Fax No.	**:**	571-273-0140
Attention	**:**	**MAIL STOP Assignment** Commissioner for Patents
From	**:**	Jiawei Huang, Reg. No. 43,330
MESSAGE	**:**	Enclosed herewith is a Recordation Cover Sheet with Assignment in 3 pages.

Sir:

I hereby certify that this correspondence is being facsimile transmitted to the Patent and Trademark Office on **July 13, 2007** at the above indicated fax number.

Sign by: ______________________
Michelle Chang
